

# United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/604,995	08/29/2003	Thomas R. Bednar	BUR920020107US1	1994
21918 7	7590 03/23/2006		EXAMINER	
DOWNS RACHLIN MARTIN PLLC			ROSSOSHEK, YELENA	
199 MAIN ST	REET		ART UNIT	PAPER NUMBER
P O BOX 190			ART OIVIT	TATER NOMBER
BURLINGTO	N, VT 05402-0190		2825	
			D. TENAMED 02/02/000	_

DATE MAILED: 03/23/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	1				
Office Action Commence	10/604,995	BEDNAR ET AL.					
Office Action Summary	Examiner	Art Unit					
	Helen Rossoshek	2825					
The MAILING DATE of this communication apperiod for Reply	pears on the cover sheet w	ith the correspondence address					
A SHORTENED STATUTORY PERIOD FOR REPL WHICHEVER IS LONGER, FROM THE MAILING D.  - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period.  - Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNI 136(a). In no event, however, may a will apply and will expire SIX (6) MO e, cause the application to become A	ICATION. reply be timely filed  NTHS from the mailing date of this communication BANDONED (35 U.S.C. § 133).					
Status							
1)⊠ Responsive to communication(s) filed on 03 J	lanuary 2006						
	s action is non-final.						
· <u> </u>	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practice under	·	•					
Disposition of Claims	_x parto Quajio, 1000 0.	7. 11, 100 0.0.210.					
4) Claim(s) 1020 is/are pending in the application							
4a) Of the above claim(s) is/are withdra	iwn from consideration.						
5) Claim(s) is/are allowed.							
6)⊠ Claim(s) <u>1-8,10-15 and 17-20</u> is/are rejected.							
7)⊠ Claim(s) <u>9 and 16</u> is/are objected to.							
8) Claim(s) are subject to restriction and/o	or election requirement.						
Application Papers							
9)☐ The specification is objected to by the Examine	er.						
10)☐ The drawing(s) filed on is/are: a)☐ acc	cepted or b) objected to	by the Examiner.					
Applicant may not request that any objection to the	drawing(s) be held in abeya	nce. See 37 CFR 1.85(a).					
Replacement drawing sheet(s) including the correct	ction is required if the drawing	y(s) is objected to. See 37 CFR 1.121	(d).				
11) The oath or declaration is objected to by the E	xaminer. Note the attache	d Office Action or form PTO-152.					
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:	•	§ 119(a)-(d) or (f).					
1. Certified copies of the priority documen							
2. Certified copies of the priority documen							
3. Copies of the certified copies of the prior	· ·	received in this National Stage					
application from the International Burea							
* See the attached detailed Office action for a list	t of the certified copies not	received.					
Attachment(s)							
1) Notice of References Cited (PTO-892)	4) Interview	Summary (PTO-413)					
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(	s)/Mail Date					
<ol> <li>Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)</li> <li>Paper No(s)/Mail Date</li> </ol>	5)  Notice of I 6)  Other:	Informal Patent Application (PTO-152)					

#### **DETAILED ACTION**

1. This office action is in response to the Application 10/604,995 filed 08/29/2003.

- 2. Claims 1-20 remain pending in the Application.
- 3. Applicant's arguments, see amendment, filed 01/03/2006, with respect to the rejection(s) of claim(s) 1-8, 10-15 and 17-20 under 35 USC § 102 have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made.

### Claim Objections

4. Claims 2-9, 11-17, 19 and 20 are objected to because of the following informalities: mentioned claims have insufficient antecedent basis issue. Each of this claims starts with indefinite article "An" or "A", which should be replaced by —The--

Claims 2 and 19 are objected to because of the following informalities: it is not clear what the Applicant intend to mean by "each of at least some of said plurality of wires . . ."

Appropriate correction is required.

## Claim Rejections - 35 USC § 102

5. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

<sup>(</sup>b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Art Unit: 2825

6. Claims 1, 10 and 18 rejected under 35 U.S.C. 102(b) as being anticipated by Jacobs et al. (US Patent 4,811,082).

With respect to claims 1, 10 Jacobs et al. teaches an integrated circuit having a plurality of circuits that include at least one I/O circuit and at least one logic circuit (col. 4, II.22-27), comprising: a) a contact layer having a plurality of contacts for electrically connecting the integrated circuit to packaging within layer with solder balls 30 to make interconnections with integrated circuits 32 as shown on the Fig. 2 (col. 13, II.25-28); b) a power grid comprising a plurality of metal layers for providing power to the at least one I/O circuit and the at least one logic circuit within plurality of power lines 45, 45a, 46, 46a, 48, 48a shown on the Fig. 2 for providing power for semiconductor device 32 on the power planes 23, 25 (col. 9, II.20-25, II.45-48); c) a semiconductor device layer in electrical communication with said power grid within semiconductor segments 32 shown on the Fig. 2, wherein semiconductor segments 32 include internal circuitry (col. 8, II.15-16-18) and interconnected to the power planes 23 and 25 (col. 8, II.23-25); and d) a wiring layer interposed between said contact layer and said power grid and electrically connecting said plurality of contacts with said power grid as shown on the Fig. 2, wherein wiring layer 19 is interposed between contact layer where contacts 30 are disposed and power grid 23 within power lines 45A (col. 8, II.42-45), said wiring layer including a plurality of wires each having a length extending partly along a first direction and partly along a second direction different from said first direction within wiring layer 19, wherein wiring layer 19 has a plurality of wires (col. 8, , II.47-50) as shown on the Fig. 2 (above via 14), wherein wires of the wiring layer 19 having width and length

Art Unit: 2825

extending in first direction and perpendicular to the first direction as an other direction as shown on the Fig. 2.

With respect to claim 18 Jacobs et al. teaches a device as shown on the Fig. 2, comprising: a) a power supply within power planes 11 shown on the Fig. (col. 11, II.45-47); and b) an integrated circuit having at least one I/O circuit and at least one logic circuit, said integrated circuit comprising: i) a contact layer having a plurality of contacts in electrical communication with said power supply within layer with solder balls 30 to make interconnections with integrated circuits 32 as shown on the Fig. 2 (col. 13, II.25-28); ii) a power grid comprising a plurality of metal layers for providing power to said at least one I/O circuit and said at least one logic circuit within plurality of power lines 45, 45a, 46, 46a, 48, 48a shown on the Fig. 2 for providing power for semiconductor device 32 on the power planes 23, 25 (col. 9, II.20-25, II.45-48); iii) a semiconductor device layer in electrical communication with said power grid within semiconductor segments 32 shown on the Fig. 2, wherein semiconductor segments 32 include internal circuitry (col. 8, II.15-16-18) and interconnected to the power planes 23 and 25 (col. 8, II.23-25); and iv) a wiring layer interposed between said contact layer and said power grid and electrically connecting at least some of said contacts with said power grid as shown on the Fig. 2, wherein wiring layer 19 is interposed between contact layer where contacts 30 are disposed and power grid 23 within power lines 45A (col. 8, II.42-45), said wiring layer including a plurality of wires each having a length extending partly along a first direction and partly along a second direction different from said first direction within wiring layer 19, wherein wiring layer 19 has a plurality of wires (col. 8, , II.47-50) as shown on the Fig. 2 (above via 14), wherein wires of the wiring layer 19 having width and length extending in first direction and perpendicular to the first direction as an other direction as shown on the Fig. 2.

#### Claim Rejections - 35 USC § 103

- 7. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 8. Claims 2-4, 6-8, 11, 12, 14, 15, 17, 19, 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Jacobs et al. as applied to claims 1, 10 and 18 above, and further in view of Tsuyuki (US Patent 6,404,026).

With respect to claims 2-8, 11-15, 17, 19, 20 Jacobs et al. teaches the limitations from which the claims depend. However Jacobs et al. lacks the specifics regarding configuration of the wires. Tsuyuki teaches:

Claims 2 and 19: each of at least some of the plurality of wires have a ring-shaped configuration within the fixed potential wiring layers 18a and 18b having the shape of ring and extending in a rectangular manner, wherein wires can be extended in two different directions (col. 9, II.48-50);

Claims 3 and 11: the ring-shaped configuration is rectangular within the fixed potential wiring layers 18a and 18b having the shape of ring and extending in a rectangular manner, wherein wires can be extended in two different directions (col. 9, II.48-50);

Art Unit: 2825

Claims 5 and 13: the plurality of contacts includes a plurality of first contacts and a plurality of second contacts located alternatively with respect to the plurality of first contacts along a plurality of lines, the wiring layer including a plurality of first wires and a plurality of second wires wherein each of the plurality of second wires is laterally spaced from a corresponding one of the plurality of first wires, and each of the plurality of first wires is located on one side of a corresponding one of the plurality of lines and a corresponding one of the plurality of second wires is located on the opposite side of the corresponding one of the plurality of lines within the fixed potential wiring layers 18a and 18b having the shape of ring and extending in a rectangular manner, wherein wires can be extended in two different directions (col. 9, II.48-50);

Claims 4, 12 and 20: at least some of the ones of the plurality of wires having the ring-shaped configuration are arranged concentrically with one another (col. 9, II.50-57); Claim 6: the plurality of wires is arranged in concentric rings within the semiconductor device having ability of the different configurations of the fixed potential wiring layer (ring) (col. 9, II.50-57);

Claims 7 and 14: the plurality of wires includes a plurality of Vdd wires and a plurality of ground wires within the fixed potential wiring layers 18a and 18b shown on the Figs, 2, 3 and 5, wherein potentials may be set to a power and ground contacts (col. 4, II.58-62; col. 6, II.65-67);

Claims 8 and 15: a plurality of Vddx wires within the fixed potential wiring layers 18a and 18b shown on the Figs, 2, 3 and 5, wherein the fixed potential wiring layers 18a

Page 7

(col. 6, II.60-65);

Claim 17: the power grid comprises a plurality of layers each comprising wires having longitudinal axes all extending in the same direction within the fixed potential wiring layers 18a and 18b having the shape of ring and extending in a rectangular manner, wherein wires can be extended in two different directions (col. 9, II.48-50), wherein the extension of the wiring direction may be in any configuration (col. 9, II.50-57). It would have been obvious to one of ordinary skill in the art at the time the invention was made to have used Tsuyuki to teach the specifics Jacobs et al. does not

### Allowable Subject Matter

teach, because of flexibility and various of effects and functions (col. 11, II.52-54).

8. Claims 9, 16 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. Prior art of record does not teach plurality of contacts is arranged in a square pattern having diagonal symmetry and major axis symmetry.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Helen Rossoshek whose telephone number is 571-272-1905. The examiner can normally be reached on 7:30-4:30.

Art Unit: 2825

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Jack Chiang can be reached on 571-272-7483. The fax phone number for

the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the

Patent Application Information Retrieval (PAIR) system. Status information for

published applications may be obtained from either Private PAIR or Public PAIR.

Status information for unpublished applications is available through Private PAIR only.

For more information about the PAIR system, see http://pair-direct.uspto.gov. Should

you have questions on access to the Private PAIR system, contact the Electronic

Business Center (EBC) at 866-217-9197 (toll-free).

Examiner Helen Rossoshek Page 8

AU 2825

SUPERVISORY PATENT EXAMINER